

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Seishi Ohashi	03/22/2013
RECEIVING PARTY DATA	
Name:	Sumitomo Bakelite Co., Ltd.
Street Address:	2-5-8 Higashi-Shinagawa, Shinagawa-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	140-0002
PROPERTY NUMBERS Total: 2	
Property Type	Number
Application Number:	13741809
PCT Number:	US1321559
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ATTORNEY DOCKET NUMBER:	ADD211-0001A US
NAME OF SUBMITTER:	Balaram Gupta
Total Attachments: 2 source=EFS_SBAssignment#page1.tif source=EFS_SBAssignment#page2.tif	

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ASSIGNMENT

WHEREAS, as a below named inventor, I have invented certain new and useful improvements in

THERMO-OXIDATIVELY STABLE, SIDE CHAIN POLYETHER FUNCTIONALIZED
POLYNORBORNENES FOR MICROELECTRONIC AND OPTOELECTRONIC
DEVICES AND ASSEMBLIES THEREOF

(Invention Title)

for which I have this day executed an application for a United States Patent (hereinafter "said application").

AND/OR

for which an application for a United States Patent was filed on 01/15/2013 (mm/dd/yyyy) and bears Application Number 13/741,809 (hereinafter "said application").

AND/OR

for which an international patent application was filed under the Patent Cooperation Treaty on 01/15/2013 (mm/dd/yyyy), bearing Application No. PCT/US2013/021559 (hereinafter "said application").

AND, WHEREAS, Sumitomo Bakelite Co., Ltd., having a place of business at 2-5-8 Higashi-Shinagawa, Shinagawa-ku, Tokyo, Japan 140-0002, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignee the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.

I covenant that I am the lawful owner(s) of said application, inventions and improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make this Assignment.

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignee or by counsel for said assignee to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs,

executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignee.

1. FULL NAME OF ASSIGNOR:

RESIDENCE:

Seishi Ohashi

Tokyo, Japan

EXECUTED this 22nd day of March, 2013

Seishi Ohashi

SIGNATURE

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2. FULL NAME OF ASSIGNOR:

RESIDENCE:

EXECUTED this \_\_\_ day of \_\_\_\_\_, 2013

\_\_\_\_\_  
SIGNATURE

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3. FULL NAME OF ASSIGNOR:

RESIDENCE:

EXECUTED this ___ day of _____, 2013

SIGNATURE

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Checked Box indicates 1 additional page(s) for inventor signatures.